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Mullish

501.36931CX1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: IWASAKI, et al  
Serial No.: 09/985,904  
Filed: November 6, 2001  
For: SEMICONDUCTOR DEVICE HAVING LAYERED  
INTERCONNECT STRUCTURE WITH A COPPER OR PLATINUM  
CONDUCTING FILM AND A NEIGHBORING FILM (As Amended)  
Group Art Unit: 2813  
Examiner: Stephen W. Smoot

SUPPLEMENTING SUBMISSION UNDER 37 CFR § 1.114  
(AMENDMENT)

Mail Stop  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

June 11, 2003

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JUN 13 2003  
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Sir:

Please further amend the above-identified application, prior to further examination thereof, and as a Supplementing Submission for the concurrently filed Request for Continued Examination (RCE) Transmittal, as follows:

IN THE CLAIMS:

Please add the following new claims to the application:

15. A semiconductor device having a layered interconnection structure according to claim 14, wherein said insulating film is a silicon oxide film.

16. A semiconductor device having a layered interconnection structure according to claim 13, wherein said insulating film is a silicon oxide film.--